

PMP21002_RevA_BOM.xls						
001						
09/18/2017						
PMP21002 REV A Bill of Materials						
Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C19	1	10pF	GRM1555C1H100JA01D	MuRata	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C17	1	47pF	GRM1555C1E470JA01D	MuRata	CAP, CERM, 47 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
C21	1	1000pF	GRM188R71H102KA01D	MuRata	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0603	0603
C16, C18	2	0.01uF	GRM188R71C103KA01D	MuRata	CAP, CERM, 0.01 µF, 16 V, +/- 10%, X7R, 0603	0603
C20, C22	2	0.047uF	C1608X7R1H473K080AA	TDK	CAP, CERM, 0.047 µF, 50 V, +/- 10%, X7R, 0603	0603
C9	1	0.1uF	GCM188R71H104KA57D	MuRata	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	0603
C10, C13	2	100pF	GRM21A5C2E101JW01D	MuRata	CAP, CERM, 100 pF, 250 V, +/- 5%, C0G/NP0, 0805	0805
C4, C6, C15	3	0.1uF	C2012X7R2A104K125AA	TDK	CAP, CERM, 0.1 µF, 100 V, +/- 10%, X7R, 0805	0805
C11, C14	2	1uF	GRM21BR71E105KA99L	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0805	0805
C5	1	2.2uF	GRM32ER72A225KA35L	MuRata	CAP, CERM, 2.2 µF, 100 V, +/- 10%, X7R, 1210	1210
C7	1	4.7uF	C3225X7R1H475K250AB	TDK	CAP, CERM, 4.7 µF, 50 V, +/- 10%, X7R, 1210	1210
C1, C12	2	4700pF	1812GC472KA1	AVX	CAP, CERM, 4700 pF, 2000 V, +/- 10%, X7R, 1812	1812
C3	1	47uF	EEE-FK1V470P	Panasonic	CAP, AL, 47 µF, 35 V, +/- 20%, 0.36 ohm, AEC-Q200 Grade 2, SMD	SMT Radial D
C2	1	22uF	EEE-FK2A220P	Panasonic	CAP, AL, 22 µF, 100 V, +/- 20%, 1.3 ohm, AEC-Q200 Grade 2, SMD	SMT Radial F
D1	1		PDU620-13	Diodes Inc.	Diode, Ultrafast, 200 V, 6 A, PowerDI5	PowerDI5
D2	1		ES2DA-13-F	Diodes Inc.	Diode, Superfast Rectifier, 200 V, 2 A, SMA	SMA
D3	1		1N4148W-7-F	Diodes Inc.	Diode, Ultrafast, 100 V, 0.15 A, SOD-123	SOD-123
D4	1	10V	MMSZ5240BS-7-F	Diodes Inc.	Diode, Zener, 10 V, 200 mW, SOD-323	SOD-323
D5, D6	2		BAS516,115	NXP Semiconductor	Diode, Switching, 100 V, 0.25 A, SOD-523	SOD-523
J1, J2	2		ED555/2DS	On-Shore Technology	Terminal Block, 3.5mm Pitch, 2x1, TH	7.0x8.2x6.5mm
L1	1	3.3uH	EPL2014-332MLB	Coilcraft	Inductor, Shielded, Ferrite, 3.3 µH, 1.1 A, 0.15 ohm, SMD	EPL2014
L2	1	270nH	EPL2014-271MLB	Coilcraft	Inductor, Shielded, Ferrite, 270 nH, 2.73 A, 0.03 ohm, SMD	EPL2014
Q1	1		BSC520N15NS3 G	Infineon Technologies	MOSFET, N-CH, 150 V, 21 A, PG-TDSON-8	PG-TDSON-8
Q2	1		FCX493TA	Diodes Inc.	Transistor, NPN, 100 V, 1 A, SOT-89	SOT-89
R13, R16	2	0	ERJ-2GE0R00X	Panasonic	RES, 0, 5%, 0.063 W, 0402	0402
R4, R6	2	4.7	CRCW04024R70JNED	Vishay-Dale	RES, 4.7, 5%, 0.063 W, 0402	0402
R12	1	100	CRCW0402100RFKED	Vishay-Dale	RES, 100, 1%, 0.063 W, 0402	0402
R11	1	1.00k	CRCW04021K00FKED	Vishay-Dale	RES, 1.00 k, 1%, 0.063 W, 0402	0402
R17	1	2.00k	CRCW04022K00FKED	Vishay-Dale	RES, 2.00 k, 1%, 0.063 W, 0402	0402
R14	1	3.40k	CRCW04023K40FKED	Vishay-Dale	RES, 3.40 k, 1%, 0.063 W, 0402	0402
R21	1	3.48k	CRCW04023K48FKED	Vishay-Dale	RES, 3.48 k, 1%, 0.063 W, 0402	0402
R18	1	4.99k	CRCW04024K99FKED	Vishay-Dale	RES, 4.99 k, 1%, 0.063 W, 0402	0402
R15	1	8.45k	CRCW04028K45FKED	Vishay-Dale	RES, 8.45 k, 1%, 0.063 W, 0402	0402
R19, R20	2	30.1k	CRCW040230K1FKED	Vishay-Dale	RES, 30.1 k, 1%, 0.063 W, 0402	0402
R8, R9, R22	3	100k	CRCW0402100FKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
R7	1	499k	CRCW0402499KFKED	Vishay-Dale	RES, 499 k, 1%, 0.063 W, 0402	0402
R3	1	20	CRCW080520R0JNEA	Vishay-Dale	RES, 20, 5%, 0.125 W, 0805	0805
R10	1	0.1	ERJ-8RSJR10V	Panasonic	RES, 0.1, 5%, 0.25 W, 1206	1206
R1	1	39k	CRCW120639K0JNEA	Vishay-Dale	RES, 39 k, 5%, 0.25 W, 1206	1206
R2, R5	2	51	CRCW251251R0JNEG	Vishay-Dale	RES, 51, 5%, 1 W, AEC-Q200 Grade 0, 2512	2512
T1	1		TOEP07-0167SG	Mentech	Transformer, 6.5 uH, SMT	10.5x12mm
T1 Alternate	0		UT38806S	UMEC	Transformer, 6.5 uH, SMT	10.5x12mm
U1	1		LM5020MM-1/NOPB	Texas Instruments	100V Current Mode PWM Controller, 10-pin MSOP	MUB10A
U2	1		HMHA2801A	Fairchild Semiconductor	Optocoupler, 3.75 kV, 80-160% CTR, SMT	Mini Flat Package
U3	1		TL431AIDBVR	Texas Instruments	PRECISION PROGRAMMABLE REFERENCE, DBV0005A	DBV0005A
C8	0	4.7uF	C3225X7R1H475K250AB	TDK	CAP, CERM, 4.7 µF, 50 V, +/- 10%, X7R, 1210	1210

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